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# FGH40T65UPD 650 V, 40 A Field Stop Trench IGBT

### **Features**

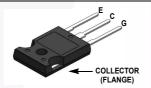
- Maximum Junction Temperature : T<sub>J</sub> = 175°C
- · Positive Temperaure Co-efficient for Easy Parallel Operating
- · High Current Capability
- Low Saturation Voltage: V<sub>CE(sat)</sub> = 1.65 V(Typ.) @ I<sub>C</sub> = 40 A
- 100% of Parts Tested I<sub>LM(2)</sub>
- · High Input Impedance
- Tightened Parameter Distribution
- RoHS Compliant
- Short Circuit Ruggedness > 5 us @25°C

## **General Description**

Using innovative field stop trench IGBT technology, Fairchild's new series of field-stop trench IGBTs offer optimum performance for solar inverter, UPS, welder, and digital power generator where low conduction and switching losses are essential.

## **Applications**

- · Solar Inverter, UPS, Welder, Digital Power Generator
- · Telecom, ESS





# **Absolute Maximum Ratings**

Symbol	Description		Ratings	Unit	
V <sub>CES</sub>	Collector to Emitter Voltage		650	V	
V <sub>GES</sub>	Gate to Emitter Voltage		± 20	V	
*GES	Transient Gate to Emitter Voltage		± 25	V	
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 25°C	80	A	
	Collector Current	@ T <sub>C</sub> = 100°C	40	A	
I <sub>CM (1)</sub>	Pulsed Collector Current		120	А	
I <sub>LM (2)</sub>	Clamped Inductive Load Current	@ T <sub>C</sub> = 25°C	120	A	
l <sub>F</sub>	Diode Forward Current	@ T <sub>C</sub> = 25°C	40	A	
	Diode Forward Current	@ T <sub>C</sub> = 100°C	20	A	
I <sub>FM(1)</sub>	Pulsed Diode Maximum Forward Current		120	A	
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	268	W	
	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	134	W	
SCWT	Short Circuit Withstand Time @ T <sub>C</sub> = 25°C		5	us	
T <sub>J</sub>	Operating Junction Temperature		-55 to +175	°C	
T <sub>stg</sub>	Storage Temperature Range		-55 to +175	°C	
T <sub>L</sub>	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C	

Notes:
1: Repetitive rating: Pulse width limited by max. junction temperature

2: Ic = 120 A, Vce = 400 V, Rg = 15  $\Omega$ 

## **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}(IGBT)$	BT) Thermal Resistance, Junction to Case		0.56	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	1.71	°C/W
R <sub>0JA</sub> Thermal Resistance, Junction to Ambient		-	40	°C/W

# **Package Marking and Ordering Information**

Part Number	Part Number Top Mark		Packing Method	Reel Size	Reel Size Tape Width	Quantity
FGH40T65UPD	FGH40T65UPD	TO-247 A03	Tube	N/A	N/A	30

# Electrical Characteristics of the IGBT T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics					
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	650	-	-	V
$\frac{\Delta BV_CES}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 250 uA	-	0.65	-	V/°C
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0 V$	/-	-	250	μΑ
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	±400	nA
On Charac	eteristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	I <sub>C</sub> = 40 mA, V <sub>CE</sub> = V <sub>GE</sub>	4.0	6.0	7.5	V
OL(III)		I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	-	1.65	2.3	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V, T <sub>C</sub> = 175°C	-	2.1	-	V
Dynamic C	Characteristics					
C <sub>ies</sub>	Input Capacitance		-	2730	3630	pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz	-	82	110	pF
C <sub>res</sub>	Reverse Transfer Capacitance	- I = I IVIDZ	-	48	72	pF
Switching	Characteristics		•			
t <sub>d(on)</sub>	Turn-On Delay Time		-	20	26	ns
t <sub>r</sub>	Rise Time		-	26	34	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 40 \text{ A},$	-	144	187	ns
t <sub>f</sub>	Fall Time	$R_G$ = 7 Ω, $V_{GE}$ = 15 V, Inductive Load, $T_C$ = 25°C	-	17	22	ns
E <sub>on</sub>	Turn-On Switching Loss	maddive Lodd, 16 20 0	-	1.59	2.1	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	0.58	0.76	mJ
E <sub>ts</sub>	Total Switching Loss		-	2.17	2.86	mJ
t <sub>d(on)</sub>	Turn-On Delay Time		-	19	-	ns
t <sub>r</sub>	Rise Time		-	38	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 40 \text{ A},$	-	153	- /	ns
t <sub>f</sub>	Fall Time	$R_G = 7 \Omega$ , $V_{GE} = 15 V$ , Inductive Load, $T_C = 175^{\circ}C$	-	60	-	ns
E <sub>on</sub>	Turn-On Switching Loss		-	1.84	- \	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	0.98	-	mJ
E <sub>ts</sub>	Total Switching Loss		-	2.82	-	mJ
T <sub>SC</sub>	Short Circuit Withstand Time	$V_{GE}$ = 15 V, $V_{CC}$ =400 V, $R_{G}$ = 10 $\Omega$	5	-	-	us
Q <sub>g</sub>	Total Gate Charge		-	177	265	nC
Q <sub>ge</sub>	Gate to Emitter Charge	V <sub>CE</sub> = 400 V, I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	-	23	35	nC
Q <sub>gc</sub>	Gate to Collector Charge	GE - 10 V	-	100	150	nC

# Electrical Characteristics of the Diode T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Unit
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> = 20 A	$T_C = 25^{\circ}C$	-	2.1	2.7	V
V FM	2.000 . 0		T <sub>C</sub> = 175°C	-	1.9	-	]
E <sub>rec</sub>	Reverse Recovery Energy		T <sub>C</sub> = 175°C	-	96	-	uJ
t	Diode Reverse Recovery Time	I <sub>F</sub> = 20 A, di <sub>F</sub> /dt = 200 A/μs	T <sub>C</sub> = 25°C	-	33	43	ns
Diode Reverse Recovery	2.000 1.010.00 1.00010.) 1	ης – 20 Λ, αιριαι – 200 Λιμο	T <sub>C</sub> = 175°C	-	128	-	
Q <sub>rr</sub>	Diode Reverse Recovery Charge		T <sub>C</sub> = 25°C	-	53	74	nC
~11	2.535		T <sub>C</sub> = 175°C	-	341	-	

Figure 1. Typical Output Characteristics

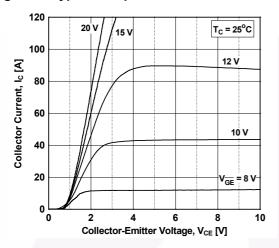


Figure 3. Typical Saturation Voltage Characteristics

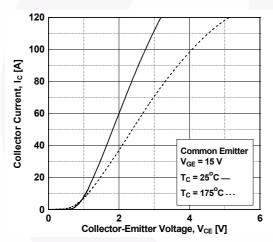
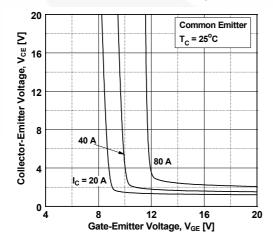


Figure 5. Saturation Voltage vs.  $V_{\text{GE}}$ 



**Figure 2. Typical Output Characteristics** 

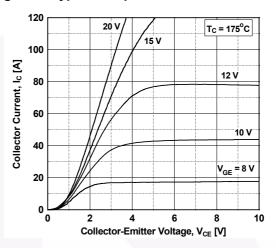


Figure 4. Saturation Voltage vs. Case
Temperature at Variant Current Level

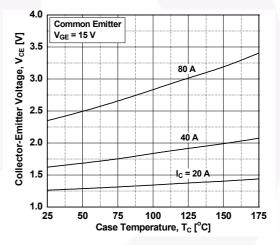


Figure 6. Saturation Voltage vs. V<sub>GE</sub>

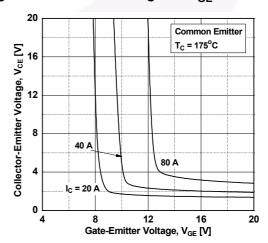


Figure 7. Capacitance Characteristics

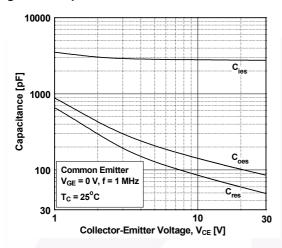


Figure 9. Turn-on Characteristics vs.
Gate Resistance

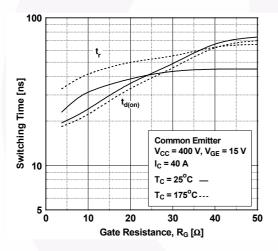


Figure 11. Switching Loss vs.

Gate Resistance

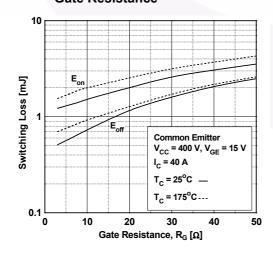


Figure 8. Gate charge Characteristics

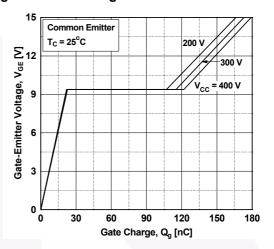


Figure 10. Turn-off Characteristics vs. Gate Resistance

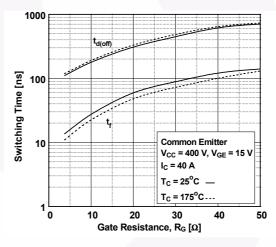


Figure 12. Turn-on Characteristics vs. Collector Current

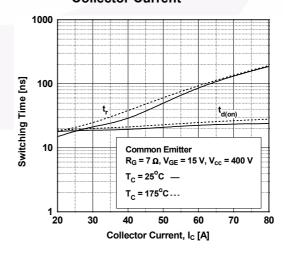


Figure 13. Turn-off Characteristics vs. Collector Current

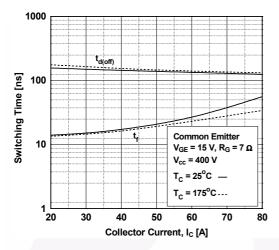


Figure 14. Switching Loss vs. Collector Current

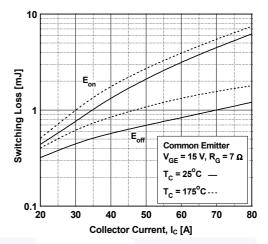


Figure 15. Load Current vs. Frequency

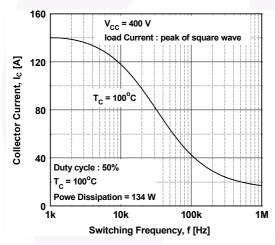


Figure 16. SOA Characteristics

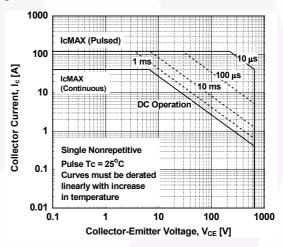


Figure 17. Forward Characteristics

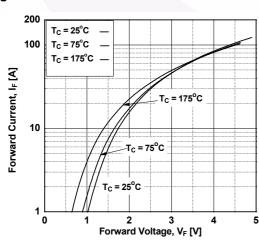


Figure 18. Reverse Revovery Current

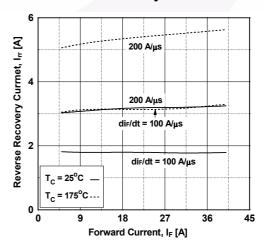


Figure 19. Reverse Recovery Time

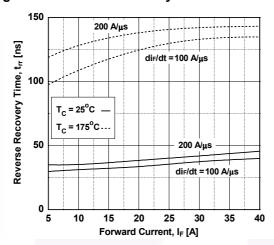


Figure 20. Stored Charge

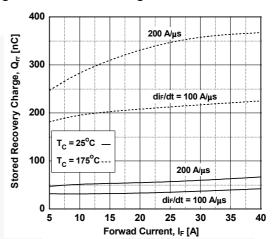


Figure 21. Transient Thermal Impedance of IGBT

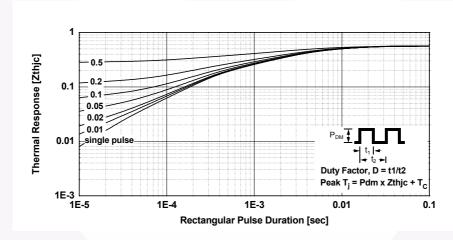
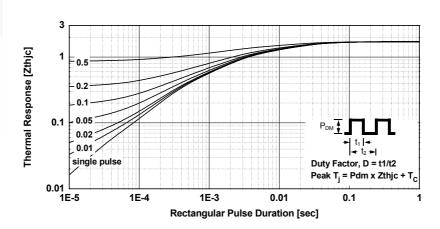
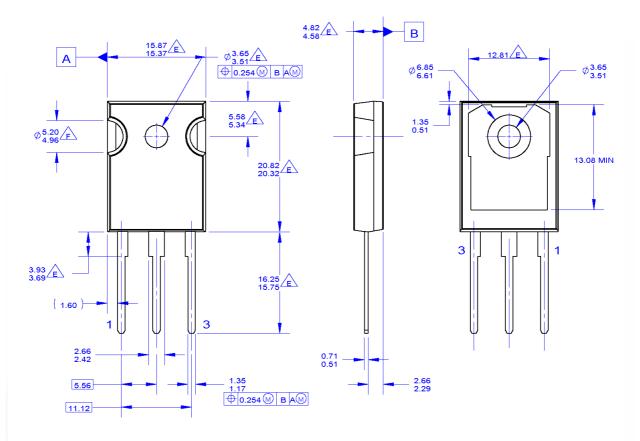


Figure 22. Transient Thermal Impedance of Diode



## **Mechanical Dimensions**



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. PACKAGE REFERENCE: JEDEC TO-247,
- ISSUE E, VARIATION AB, DATED JUNE, 2004. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
- FLASH, AND TIE BAR EXTRUSIONS.
  ALL DIMENSIONS ARE IN MILLIMETERS
- D. DRAWING CONFORMS TO ASME Y14.5 1994
- E DOES NOT COMPLY JEDEC STANDARD VALUE
- NOTCH MAY BE SQUARE DRAWING FILENAME: MKT-TO247A03\_REV03

Figure 23. TO-247, MOLDED, 3 LEAD, JEDEC VARIATION AB (Active)

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Dimensions in Millimeters





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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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